

ABSTRACT OF THE DISCLOSURE

A focusing cup is directly glued to two or more preformed folded metal frames. Parts of the top surfaces of the folded metal frames contact the electrodes of semiconductor device placed inside the focusing cup. The bottoms of the metallic frames serve as the bottom contacts for surface mounting to a motherboard. The preformed metallic frames need not withstand the stress of folding and the package can be made thinner than prior art. The elimination of the through holes makes the package narrower.